



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Donald C. Abbott Docket No.: TI-28098
Serial No.: CPA of 09/525,105 Examiner: TBD
Filed: Herewith Art Unit: TBD
For: Semiconductor Circuit Assembly Having a Plated Leadframe Including
Gold Selectively Covering Areas to be Soldered (As Amended)

16
Amend C
Ref No 10/10/02
OCT -3 2002
TECHNOLOGY CENTER 2800

Preliminary Amendment

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that this correspondence is being deposited with the
U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on
9-27-02

Marianna Smith
Marianna Smith

Dear Sir:

Please enter the following amendments prior to examination of the instant application.

In the Claims:

10/11/2002 AJENKINS:00000002 200668 09525105
01 TCI 102 1. (amended) A leadframe for use with packaged integrated circuit chips comprising:

168.00 CH gold selectively plated on segments of said leadframe intended for solder attachment.

2. (amended) A leadframe for use with packaged integrated circuit chips, having a chip mount pad and a plurality of lead segments, comprising:

a leadframe base made of copper or copper alloy;

a first layer of nickel deposited on said copper or copper alloy;

a layer of an alloy of nickel and palladium on said first nickel layer;